Lecture 8

Equations of State, Equilibrium and Einstein Relationships and Generation/Recombination

Reading:

(Cont'd) Notes and Anderson² sections 3.4-3.11

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Consider a non-uniformly doped semiconductor.



Since the electrons (or holes) are free to move anywhere in the material, the average energy of the electrons can not change. If the average energy did change from one position to another, there would be a net motion of electrons from high energy toward low energy.

E_f must be constant when no current flows!

•Remember:

•No net current can flow otherwise we have a "perpetual motion machine".

•But dEc/dx is nonzero so we have a drift current component.

•The drift current component MUST be balanced by a diffusion current component!



Additionally, since electrons and holes operate "independently of each other",

 $J_n|_{\text{Diffusion}} + J_n|_{\text{Drift}} = 0$ and $J_p|_{\text{Diffusion}} + J_p|_{\text{Drift}} = 0$

•Thus, for non-uniform doping in equilibrium, we have:

•E_f is constant

•No net current

•Carrier Concentration gradients that result in a diffusion current component.

•A "Built in" electric field that result in a drift current component.

•BOTH electron and hole components must sum to zero. I.E. $J_n = J_p = 0$

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Consider the case for electrons:

$$J_{n|Drift} + J_{n|Diffusion} = q\mu_n nE + qD_n \frac{dn}{dx} = 0 \qquad (*)$$

but
$$E = \frac{1}{q} \frac{dE_i}{dx}$$
 and $n = n_i e^{(Ef - Ei)/kT}$ and $\frac{dE_f}{dx} = 0$

Thus, taking the derivative of n,

$$\frac{dn}{dx} = \frac{n_i}{kT} e^{(Ef - Ei)/kT} \left(\frac{dE_f}{dx} - \frac{dE_i}{dx} \right) = \frac{dn}{dx} = -\frac{n_i}{kT} e^{(Ef - Ei)/kT} \left(\frac{dE_i}{dx} \right)$$

$$=-\frac{q}{kT}nE$$

Thus (*) becomes,

$$\mu_n(qnE) - (qnE)D_n \frac{q}{kT} = 0$$

or,

$$\frac{D_n}{\mu_n} = \frac{kT}{q} \qquad Likewise for holes, \quad \frac{D_p}{\mu_p} = \frac{kT}{q} \qquad \text{Einstein} \\ \text{Relationship}$$

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Other "need to knows"

kT = Energy (thermal energy)

 $= (8.617 \times 10^{-5} \text{ eV/K}) (\text{T in K})$ [eV]

 $= (8.617 \times 10^{-5} \text{ eV/K}) (1.6 \times 10^{-19} \text{ J/eV})(\text{T in K})$ [J]

kT/q = Voltage (thermal voltage)

= J/coulomb

=J/(J/V)=volts

 $D_n = Diffusion \ coefficient \ [cm²/second]$

Example: For Si, $\mu_n \sim 1358 @ 27 C ====>$ $D_n = (0.0259 V) (1358 cm^2/V\text{-second}) = 35.2 cm^2/\text{Second}$

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Direct verses Indirect Bandgaps



The energy required to liberate an electron from the atom (the energy bandgap) is the same in all "escape directions" (directions that an electron can leave the atom).

Example: Electrons directed toward a neighboring atom would have a high escape energy, while electrons directed toward a channel in the crystal (a hole through the crystal) would have a lower escape energy.

Thus, the energy band diagram is actually a function of momentum. Additionally, both energy and momentum (directed mass motion) must be conserved during any transition.

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Direct verses Indirect Bandgaps

Direct Bandgap Indirect Bandgap Conduction **↓**E band Conduction **Probability of a** band "direct transition" $E_{g} = 1.4 \text{ eV}$ $E_{g} = 1.1 \, \text{eV}$ from valence band to р conduction Valence band is high! Valence band band Si GaAs (b)(a)

Probability of a "direct transition" from valence band to conduction band is low but if the valence electron is on an atom vibrating in a direction (I.e. has momentum) that lowers the energy required, the probability increases!

FIGURE 1-12

Energy-band diagram with energy vs. momentum for (a) GaAs (direct) and (b) Si (indirect).

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Direct verses Indirect Bandgap variations in Light Absorption

Polar materials like GaAs, InP, GaN etc... tend to be better at absorbing light. No lattice vibration is needed to absorb the light=direct gap.



Direct verses Indirect Bandgap variations in Light Absorption

After the atoms move apart from their equilibrium positions, the core is displaced from the electron cloud. The photon's electric field then resonates (fields are additive) with the atom core - electron cloud dipole and thus is absorbed.

+0 U 0 Electron cloud Magnitude of Electric Field of a Photon of light

Covalent materials like Si, Ge etc... tend to be poor light absorbers. A lattice vibration is needed to induce a dipole in the crystal before the light can be absorbed=indirect gap.

3 Recombination and 3 Generation Mechanisms...



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Figure 3.16 Near-midgap energy levels introduced by some common impurities in Si. When an impurity introduces multiple levels, one of the levels tends to dominate in a given semiconductor sample. **PERIODIC TABLE OF THE ELEMENTS**



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Recombination Mechanisms

•Band to Band or "direct" (directly across the band) recombination

•Does not have to be a "direct bandgap" material, but is typically very slow in "indirect bandgap" materials.

•Basis for light emission devices such as semiconductor LASERs, LEDs, etc...

<u>Photon (single</u> <u>particle of light)</u> or multiple phonons (single quantum of lattice vibration equivalent to saying thermal energy)

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Recombination Mechanisms



•Recombination-Generation (R-G) Center recombination.

•Also known as Shockley-Read-Hall (SRH) recombination.

•Two steps: 1.) 1st carrier is "trapped" (localized) at an unintentional (or intentional) defect/impurity. 2.) 2nd carrier (opposite type) is attracted to the R-G center and annihilates the 1st carrier.

•Useful for creating "fast switching" devices by quickly "killing off" ehp's.

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•Auger – "pronounced O-jay" recombination.

•Requires 3 particles.

•Two steps: 1.) 1st carrier and 2nd carrier of same type collide instantly annihilating the electron hole pair (1st and 3rd carrier). The energy lost in the annihilation process is given to the 2nd carrier. 2.) 2nd carrier gives off a series of phonons until it's energy returns to equilibrium energy ($E \sim = E_c$) This process is known as thermalization.



- •Band to Band or "direct" (directly across the band) generation
- •Does not have to be a "direct bandgap" material.
- •Mechanism that results in n_i

•Basis for light absorption devices such as semiconductor photodetectors, solar cells, etc...

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•Recombination-Generation (R-G) Center generation.

•Two steps: 1.) A bonding electron is "trapped" (localized) at an unintentional defect/impurity generating a hole in the valence band. 2.) This trapped electron is then promoted to the conduction band resulting in a new ehp.

•Almost always detrimental to electronic devices. AVOID IF POSSIBLE!

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•Impact Ionization generation.

•Requires 3 particles and, typically, high electric fields (steeply bent bands).

•1st carrier is accelerated by high electric fields (or may very rarely gain enough kinetic energy on it's own) and collides with a lattice atom, knocking out a bonding electron creating an ehp.

If the origin is a high electric field, this process can lead to rapid carrier multiplication known as "avalanching". Can be very useful for very sensitive (but noisy) photodiodes.
Sets an upper limit on practical electric fields that can be tolerated in many transistors.